6-A Non-Isolated DDR/QDR Memory Bus Termination Modules





NOMINAL SIZE = 0.87 in x 0.5 in (22,1 mm x 12,57 mm)

Features

- V_{TT} Bus Termination Output (Output Tracks the System V_{REF})
- 6 A Output Current (8 A Peak)
- 3.3-V, 5-V or 12-V Input Voltage
- DDR & QDR Compatible
- On/Off Inhibit (for V_{TT} Standby)
- Under-Voltage Lockout
- Operating Temp: -40 to +85 °C
- Efficiencies up to 88 %
- 50 W/in³ Power Density
- Output Over-Current Protection (Non-Latching, Auto-Reset)
- Safety Agency Approvals (Pending): UL/cUL60950, EN60950, VDE
- Point-of-Load Alliance (POLA) Compatible

Description

The PTHxx050Y are a series of readyto-use switching regulator modules from Texas Instruments designed specifically for bus termination in DDR and QDR memory applications. Operating from either a 3.3-V, 5-V or 12-V input, the modules generate a $V_{\rm TT}$ output that will source or sink up to 6 A of current (8 A transient) to accurately track their $V_{\rm REF}$ input. $V_{\rm TT}$ is the required bus termination supply voltage, and $V_{\rm REF}$ is the reference voltage for the memory and chipset bus receiver comparators. $V_{\rm REF}$ is usually set to half the $V_{\rm DDO}$ power supply voltage.

Both the PTHxx050Y series employs an actively switched synchronous rectifier

output to provide state-of-the-art step-down switching conversion. The products are small in size (0.87 in \times 0.5 in), and are an ideal choice where space, performance, and high efficiency are desired, along with the convenience of a ready-to-use module.

Operating features include an on/off inhibit and output over-current protection (source mode only). The on/off inhibit feature allows the $V_{\rm TT}$ bus to be turned off to save power in a standby mode of operation.

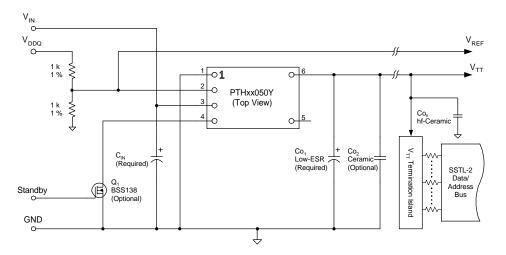
Package options include both throughhole and surface mount configurations.

Pin Configuration

| Pin | Function |
|-----|------------|
| 1 | GND |
| 2 | V_{REF} |
| 3 | V_{IN} |
| 4 | Inhibit * |
| 5 | No Connect |
| 6 | V_{TT} |

 $egin{array}{ll} Denotes & negative logic: \\ Open & = V_{TT} Output On \\ Ground & = V_{TT} Output Off \\ \end{array}$

Standard Application



 C_{in} = Required electrolytic capacitor; 220 μF (3.3-/5-V input), 560 μF (12-V input).

 $Co_{1} \ = Required \ low-ESR \ electrolyitic \ capacitor; 470 \ \mu F \ (3.3-/5-V \ input), 940 \ \mu F \ (12-V \ input).$

Co₂ = Ceramic capacitance for optimum response to a 3-A (±1.5-A) load transient.; 200 μF (3.3-/5-V input), 400 μF (12-V input).

Con = Distributed hf-ceramic decoupling capacitors for V_{TT} bus; as recommended for DDR memory appications.

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Ordering Information

| Input Voltage (PTH 050Yxx) | | Package Options (PTHxx050Y□□) (1) | | | |
|----------------------------|---------------|-----------------------------------|-------------------|--------------|--|
| Code | Input Voltage | Code | Description | Pkg Ref. (2) | |
| 03 | 3.3 V | AH | Horiz. T/H | (EUU) | |
| 05 | 5 V | AS | SMD, Standard (3) | (EUV) | |
| 12 | 12 V | | | | |

Notes: (1) Add "T" to end of part number for tape and reel on SMD packages only.

- (2) Reference the applicable package reference drawing for the dimensions and PC board layout
- (3) "Standard" option specifies 63/37, Sn/Pb pin solder material.

Pin Descriptions

 V_{IN} : The positive input voltage power node to the module, which is referenced to common GND.

GND: This is the common ground connection for the V_{IN} and V_{TT} power connections. It is also the 0-VDC reference for the control inputs.

V_{REF}: The module senses the voltage at this input to regulate the output voltage, V_{TT} . The voltage at V_{REF} is also the reference voltage for the system bus receiver comparators. It is normally set to precisely half the bus driver supply voltage ($V_{DDQ} \div 2$), using a resistor divider (see standard application). The Thevenin impedance of the network driving the V_{REF} pin should not exceed 500 Ω .

 V_{Π} : This is the regulated power output from the module with respect to the GND node, and the tracking termination supply for the application data and address buses. It is precisely regulated to the voltage applied to the module's $V_{\rm REF}$ input, and is active active about 20 ms after a valid input source is applied to the module. Once active it will track the voltage applied at $V_{\rm REF}$.

Inhibit: The Inhibit pin is an open-collector/drain negative logic input that is referenced to GND. Applying a low-level ground signal to this input turns off the output voltage, V_{TT}. When the Inhibit is active, the input current drawn by the regulator is significantly reduced. If the Inhibit pin is left open circuit, the module will produce an output whenever a valid input source is applied.

Environmental & Absolute Maximum Ratings (Voltages are with respect to GND)

| Characteristics | Symbols | Conditions | Min | Тур | Max | Units |
|-----------------------------|--------------|--|-------------|-----|----------------|-------|
| Control Input Voltage | $V_{ m REF}$ | | -0.3 | _ | $V_{in} + 0.3$ | V |
| Operating Temperature Range | T_a | Over V _{in} Range | -40 (i) | _ | 85 | °C |
| Solder Reflow Temperature | T_{reflow} | Surface temperature of module body or pins | | | 235 (ii) | °C |
| Storage Temperature | T_s | _ | -4 0 | _ | 125 | °C |
| Mechanical Shock | | Per Mil-STD-883D, Method 2002.3 1 msec, ½ Sine, mounted | _ | 500 | _ | G's |
| Mechanical Vibration | | Mil-STD-883D, Method 2007.2 20-2000 Hz | _ | 20 | _ | G's |
| Weight | _ | | _ | 2.9 | _ | grams |
| Flammability | _ | Meets UL 94V-O | | | | |

Notes: (i) For operation below 0 °C the external capacitors m ust bave stable characteristics. use either a low ESR tantalum, Os-Con, or ceramic capacitor.

(ii) During reflow of SMD package version do not elevate peak temperature of the module, pins or internal components above the stated maximum.



6-A Non-Isolated DDR/QDR Memory **Bus Termination Modules**

Specifications (Unless otherwise stated, T_a =25 °C; nominal V_{in}; V_{REF} =1.25 V; C_{in}, Co₁, & Co₂ =typical values; and I_o =I_omax)

| | | | | PTHxx050Y | | |
|---|---|---|--|--|------------------------|------------|
| Characteristics | Symbols | Conditions | Min | Тур | Max | Units |
| Output Current | I_{o} | Over ΔV_{REF} range, Continuous | 0 | _ | ±6 (1) | A |
| | | Repetitive pulse | _ | _ | ±8 (2) | A |
| Input Voltage Range | V _{in} | Over I _o range PTH03050Y PTH05050Y PTH12050Y | 2.95 4.5 10.8 | _ _ _ | 3.65 5.5 13.2 | V |
| Tracking Range for V _{REF} | $\Delta { m V}_{ m REF}$ | | 0.55 | _ | 1.8 | V |
| Tracking Tolerance to V _{REF} | $ V_{TT}-V_{REF} $ | Over line, load and temperature | -10 | _ | +10 | mV |
| Efficiency | η | I _o =4 A PTH03050Y PTH05050Y PTH12050Y | = | 88 87 84 | _ _ _ | % |
| $ m V_o$ Ripple (pk-pk) | V_{r} | 20 MHz bandwidth | _ | 20 | _ | mVpp |
| Over-Current Threshold | I _o trip | Reset, followed by auto-recovery | _ | 12 | _ | A |
| Load Transient Response | $egin{array}{c} {t_{tr}} \ \Delta {V_{tr}} \end{array}$ | 15 A/ μ s load step, from –1.5 A to +1.5 A (See note 5) Recovery Time V_0 over/undershoot | | 80 25 | | μSec mV |
| Under-Voltage Lockout | UVLO | V _{in} increasing PTH03050Y PTH05050Y PTH12050Y | = | 2.45 4.3 9.5 | 2.8 4.45 10.4 | V |
| | | $\begin{array}{c} V_{in} \text{decreasing} & PTH03050Y \\ PTH05050Y \\ PTH12050Y \end{array}$ | 2.2 3.4 8.8 | 2.40 3.7 9 | _ | V |
| Inhibit Control (pin4) Input High Voltage Input Low Voltage | $V_{ m IH} \ V_{ m IL}$ | Referenced to GND | V _{in} -0.5 -0.2 | _ | Open (3) 0.6 | V |
| Input Low Current | ${ m I_{IL}}$ inhibit | Pin to GND | _ | -130 | _ | μA |
| Input Standby Current | I _{in} inh | Inhibit (pin 4) to GND | _ | 10 | _ | mA |
| Switching Frequency | $f_{ m s}$ | $\begin{array}{c} \text{Over V}_{\text{in}} \& \text{I}_{\text{o}} \text{ ranges} & \text{PTH03050Y/PTH05050Y} \\ \text{PTH12050Y} \end{array}$ | 550 200 | 600 250 | 650 300 | kHz |
| External Input Capacitance | C _{in} | PTH03050Y/PTH05050Y PTH12050Y | 220 ⁽⁴⁾ 560 ⁽⁴⁾ | _ | _ | μF |
| External Output Capacitance | Co ₁ , Co ₂ | Capacitance value: non-ceramic PTH03050Y/PTH05050Y PTH12050Y | 0 | 470 ⁽⁵⁾ 940 ⁽⁵⁾ | 3,300 (6) 3,300 (6) | μF |
| | | ceramic PTH03050Y/PTH05050Y PTH12050Y | 0 | 200 ⁽⁵⁾ 400 ⁽⁵⁾ | 300 600 | μF |
| | | Equiv. series resistance (non-ceramic) | 4 (7) | _ | _ | $m\Omega$ |
| Reliability | MTBF | Per Bellcore TR-332 50 % stress, T _a =40 °C, ground benign | 6 | _ | _ | 106 Hrs |

Notes: (1) Rating is conditional on the module being directly soldered to a 4-layer PCB with 1 oz. copper. See the SOA curves or contact the factory for appropriate derating. The PTH03050Y and PTH05050Y require no derating up to 85 °C operating temperature and natural convection airflow.

(2) Up to 10 ms pulse period at 10 % maximum duty.

(3) This control pin has an internal pull-up to the input voltage Vin. If it is left open-circuit the module will operate when input power is applied. A small low-leakage (<100 nA) MOSFET is recommended for control. For further information, consult the related application note.

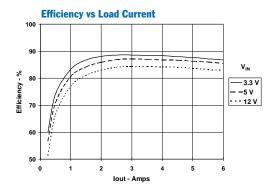
⁽⁴⁾ An input capacitor is required for proper operation. The capacitor must be rated for a minimum of 300 mA rms (750 mA rms for 12-V input) of ripple

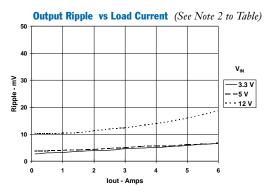
 ⁽⁵⁾ The typical value of external output capacitance value ensures that V_{TT} meets the specified transient performance requirements for the memory bus terminations. Lower values of capacitance may be possible when the measured peak change in output current is consistently less than 3 A.
 (6) This is the calculated maximum. The minimum ESR limitation will often result in a lower value. Consult the application notes for further guidance.
 (7) This is the typical ESR for all the electrolytic (non-ceramic) output capacitance. Use 7 mΩ as the minimum when using max-ESR values to calculate.

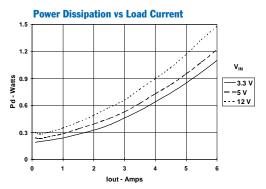
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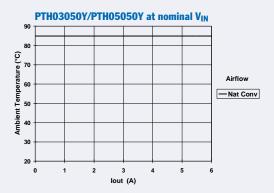
Characteristic Data; V_{REF} =1.25 V (See Note A)

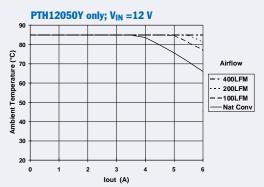






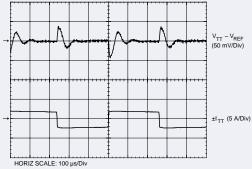
Safe Operating Area; V_{REF} =1.25 V (See Note B)





Transient Performance for △4-A Load Change

PTH03050Y: Sink to Source Transient



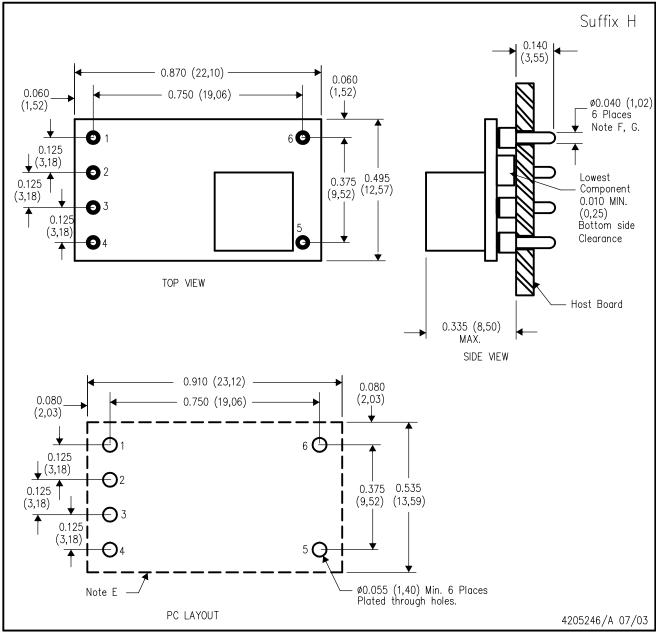
Note A: Characteristic data has been developed from actual products tested at 25°C. This data is considered typical data for the Converter.

Note B: SOA graphs represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 4 in × 4 in. double-sided PCB with 1 oz. copper.



EUU (R-PDSS-T6)

DOUBLE SIDED MODULE



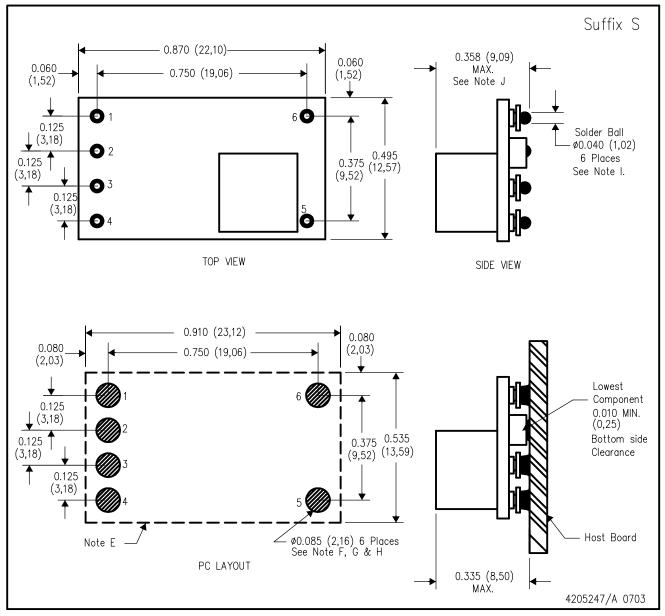
NOTES:

- A. B. All linear dimensions are in inches (mm).
- This drawing is subject to change without notice.
- C. 2 place decimals are ± 0.030 (± 0.76 mm).
- D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
- E. Recommended keep out area for user components.
- F. Pins are 0.040" (1,02) diameter with 0.070" (1,78) diameter standoff shoulder.
- G. All pins: Material Copper Alloy Finish - Tin (100%) over Nickel plate



EUV (R-PDSS-B6)

DOUBLE SIDED MODULE



NOTES: All linear dimensions are in inches (mm).

- This drawing is subject to change without notice.
- 2 place decimals are ± 0.030 (± 0.76 mm). 3 place decimals are ± 0.010 (± 0.25 mm).
- Recommended keep out area for user components.
- F. Power pin connection should utilize two or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
- Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).
- H. Pad type: Solder mask defined.
- I. All pins: Material Copper Alloy

Finish — Tin (100%) over Nickel plate Solder Ball — See product data sheet.

J. Dimension prior to reflow solder.



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